





## Target Applications

The Dragonwing IQ-9075 EVK enables developers to evaluate the industrial-grade performance of the Dragonwing IQ-9075 processor for prototype IoT solutions, including:

- Industrial Automation
- Robotics
- Autonomous Mobile Robots
- Drones
- On-Device AI
- Unmanned Aerial Vehicles (UAVs)

## Features

### AI Model Development and Prototyping

Create, test, and optimize AI models for compute, smart vision, language processing, and machine learning applications with the [Qualcomm® AI Hub](#) and its support for frameworks like ONNX Runtime, TensorFlow Lite, and PyTorch.

### Robotics and Industrial Automation

Build proof of concepts for autonomous mobile robots, unmanned aerial vehicles, drones, industrial machinery, and agricultural robotics with real-time, on-device AI decision making and execution.

### Multi-Sensor and Camera Fusion

Design multi-sensor and camera systems with real-time sensor fusion technology for surveillance, object detection, navigation, predictive maintenance, quality control, and process automation.

### High-Performance Edge Computing

Facilitate the development of edge AI solutions for industrial IoT, smart cities, retail, work/site safety, smart buildings, and healthcare.

## Ordering Information

### Part Number

**EVK-IQ9075M-STARTER-1.2**

## Specifications

Processor	Dragonwing IQ-9075 ( <a href="#">See more here</a> ) SKU: QCS9075-0-AA
Operating System	Ubuntu, Upstream Linux with Yocto Support
Memory	36 GB LPDDR5 with link ECC
Storage	128 GB UFS
PCIe/Connectivity	Wi-Fi/Bluetooth: M.2 module with connector on mainboard PCIe: 1x PCIe4 slot or expansion (switched), 1x m.2 E key (Wi-Fi) or expansion (switched)
Display	• 2x mini-DP (one with MST) • DSI flex connection (display not included)
Camera	4x MIPI CSI (C/D-PHY) flex connectors
USB	• USB Type C (host or device mode) • USB Type C (host mode) • USB 2.0 (host or device mode)
Audio	• 1x I2S mic • 2x I2S speaker amps • Additional I2S on GPIOs
Video	• Encode: up to 2x 4K60 (concurrent) or 1x 4K170 • Decode: up to 4x 4K60 (concurrent 2x 4K60) or 1x 4K275 with support for AV1, HEVC, H.264, H.265
Ethernet	RJ45 (2.5 GbE)
CAN	1x CAN-FD on LS expansion
Other I/Os on Mezzanine Connectors (1.8 V)	• 2x UART (RX/TX), 1x UART (RX/TX/CTS/RFR), 1x SAIL_UART (RX/TX) • 1x SAIL_SPI (CS0), 1x SAIL_SPI (CS0, CS1) • 5x I2C, 3x CCI_I2C, 1x SAIL_I2C • 44x SOC GPIO, 30x PMIC GPIO (After using above listed QUPs, I2S) • 6x QUP (LO/1), 3x QUP (LO-3), 1x QUP (L2/3), 1x QUP (QSPI), 1x QUP (LO-3, CS0, CS1)
TPM	ST33HTPH2x32AHE4 on mainboard
Sensors	IMU: ICM-42688
Debug/UI	FTDI
Thermal Management	Heatsink and fan
Power	DC barrel plug (20V)
Size	106 x 106 x 56 mm
Other Parts Included in Kit	Power supply and adapter included

Specifications are subject to change.

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